

REMARKS

This amendment is being filed in response to the Notice of Drawing Inconsistency with Specification dated November 29, 2007. Entry of the foregoing amendment is respectfully requested. The amendment corrects an inconsistency that exists between the drawings and the Brief Description of the Drawings in the specification. The amendment does not change the scope of the claims. Accordingly, entry of the amendment is requested.

In the specification, paragraphs have been amended on page 5. Brief Description of Fig. 10C has been added to state "FIG. 10C is a perspective view of a substrate where the aluminum pillars are dissolved with an alumina coating according to an embodiment of the present invention." Support for this change is in the Original Specification on the paragraph starting page 13, line 30. Thus, no new matter is added.

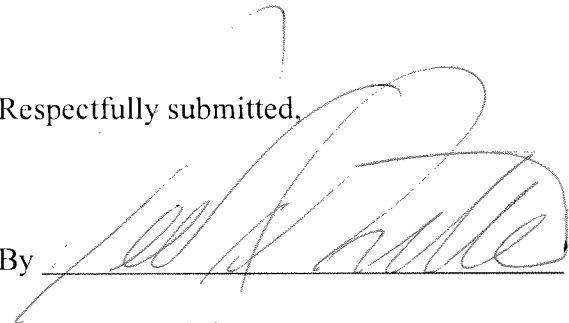
It is believed that no fees are due. In the event this is not correct, the undersigned authorizes the Commissioner to charge Deposit Account No. 19-0741.

Respectfully submitted,

Date

12-13-07

By



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FIG. 4 is a flow diagram of a more detailed process for fabricating a sensor substrate according to an embodiment of the present invention.

FIG. 5 is a flow diagram of a process for filling vias with a filler according to an embodiment of the present invention.

5 FIG. 6A is a cut-away view of a filled via according to an embodiment of the present invention.

FIG. 6B is a cut-away view of a filled via and a filled meniscus according to an embodiment of the present invention.

10 FIG. 7 is a flow diagram for filling a meniscus according to an embodiment of the present invention.

FIG. 8 is a cut-away view of a hermetically filled via with excess filler from a via and a meniscus lapped off according to an embodiment of the present invention.

FIG. 9 is a flow diagram of a process for preparing one side of a substrate to accept an IC and another side to accept a sensing element according an embodiment of the present invention.

15 FIG. 10A and 10B are perspective views of a substrate with aluminum pillars formed on top of vias without alumina and coated with an alumina coating, respectively.

FIG. 10C is a perspective view of a substrate where the aluminum pillars are dissolved with an alumina coating according to an embodiment of the present invention.

20 FIG. 11 is a perspective view of a photoresist corresponding to an electrode pattern according to an embodiment of the invention.

FIG. 12 is a flow diagram of a process for affixing an IC to an electronics side of a substrate according to an embodiment of the present invention.

FIG. 13 is a flow diagram of a process for forming a lid according to an embodiment of the present invention.

25 FIG. 14 is a flow diagram of a process for performing a gross leak test according to an embodiment of the present invention.

FIG. 15 is a flow diagram of a process for electroplating and coating the substrate according to an embodiment of the present invention.

30 FIG. 16 is a perspective view of a finally assembled sensor substrate according to an embodiment of the invention.